Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	13493	(laser beam) with (semiconductor wafer street) with (film layer$3 coat$3)	JPO	OR	ON	2005/08/31 09:09
L8	390	7 with (cut cutting divid$3)	JPO	OR	ON	2005/08/31 08:35
L9	33	8 and ((film layer$3 coat$3) near5 protect$5)	JPO	OR	ON	2005/08/31 09:19
L10	3	9 and ((film layer$3 coat$3) near5 resin$3)	JPO	OR	ON	2005/08/31 08:56
L11	5	8 and ((film layer$3 coat$3) near5 sheet)	JPO	OR	ON	2005/08/31 08:56
L12	21	8 and ((film layer$3 coat$3) near5 protect$5) and ((film layer$3 coat$3) near5 (cut cutting divid$3))	JPO	OR	ON	2005/08/31 09:08
L13	13493	(laser beam) with (semiconductor wafer street) with (film layer$3 coat$3)	JPO	OR	ON	2005/08/31 09:09
L14	61324	(laser beam) with (semiconductor wafer street) with (film layer$3 coat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:09
L15	9623	14 and ((film layer$3 coat$3) near5 protect$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:17
L16	1585	14 and (((film layer$3 coat$3) near5 protect$5) with (film layer$3 coat$3) near5 remov$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:18
L17	9	8 and ((film layer$3 coat$3) near5 protect$5) and remov$3	JPO	OR	ON	2005/08/31 09:31
L18	2	8 and ((film layer$3 coat$3) near5 water)	JPO	OR	ON	2005/08/31 09:32
L19	17	7 and (water near5 soluble)	JPO	OR	ON	2005/08/31 09:35
L20	8	7 and (liquid near3 resin)	JPO	OR	ON	2005/08/31 10:06
L21	5007	219/121.67,121.68,121.69,121.72, 121.85.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 10:07
L23	63	21 and ((wafer silicon semiconductor) same ((protect$4 near3 (film sheet coat$3))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 10:10